

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-14. (Canceled)

15. (Currently Amended) A fluid ejector, comprising:

channels formed in at least one of a first wafer, a second wafer and zero, one or more intermediate layers;

at least one cross-trench formed in at least one of the first and second wafers at the zero, one or more intermediate layers that intersects the channels to form orifices for the channels, wherein the combination of the first and second wafers on the zero, one or more intermediate layers form a wafer structure containing a plurality of fluid ejector devices;

front faces formed for the fluid devices by at least dicing into the cross-trenches such that the orifices are offset from the front faces, one of the front faces formed above the at least one cross-trench and another of the front faces formed below the at least one cross-trench.

16. (Currently Amended) The fluid ejector of claim 15, wherein the orifices are set back from the front ~~face~~-faces formed by dicing.

17. (Currently Amended) The fluid ejector of claim 15, wherein the orifices extend in front of the ~~surfaces~~-front faces formed by dicing.

18. (Original) The fluid ejector of claim 15, wherein the cross-trench is formed by reactive ion etching.

19. (Original) The fluid ejector of claim 15, wherein front faces are formed for the fluid devices by dicing at least to a depth that does not extend to the orifices.

20. (Currently Amended) A fluid ejector device, comprising:

a heater wafer containing bubble-nucleating heaters and related electronics;

a polymer layer;

a channel wafer;

at least one cross-trench formed in at least one of the heater wafer, the polymer layer, and the channel wafer that intersects the channels formed in at least one of the channel wafer, the polymer layer, and the heater wafer to form orifices for the channel, wherein the channel wafer is over the polymer layer, and the polymer layer is over the heater wafer to form a bonded structure; and

a front face formed by dicing at least into the at least one cross-trench of the bonded structure, the front face comprising the orifices.

21. (Canceled)

22. (Canceled)

23. (Original) The fluid ejector device of claim 20, wherein the at least one cross-trench is formed by reactive ion etching.

24. (Original) The fluid ejector device of claim 20, wherein the channel is flared near the orifice.

25. (Original) The fluid ejector claim 20, wherein the channel is tapered near the orifice.

26. (Currently Amended) The fluid ejector of claim 20, wherein front ~~faces are~~ face is formed for the fluid devices by dicing ~~at least~~ to a depth that does not extend to the orifices.